

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



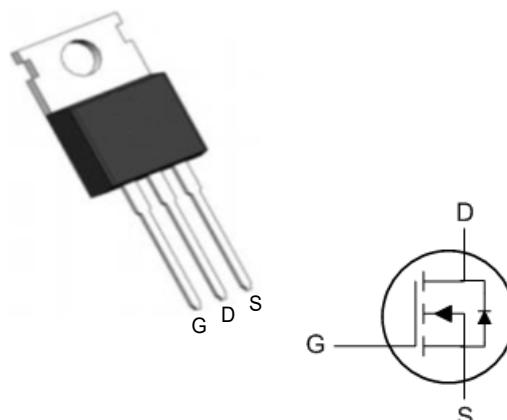
BVDSS	RDS(on)	ID
70V	5.8mΩ	120A

Description

The XR120N07T is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XR120N07T meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

TO220AB Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	70	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	120	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	72	A
I _{DM}	Pulsed Drain Current ²	480	A
EAS	Single Pulse Avalanche Energy ³	248	mJ
I _{AS}	Avalanche Current	31.25	A
P _D @T _C =25°C	Total Power Dissipation ⁴	125	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	---	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	10	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	---	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=25\text{A}$	---	5.8	7.3	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	2.4	3	3.6	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	---	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DS}}^{(\text{SS})}$	Drain-Source Leakage Current	$V_{\text{DS}}=1\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{\text{DS}}=1\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=100^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=25\text{A}$	---	---	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	---	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=25\text{A}$	---	45	---	nC
Q_{gs}	Gate-Source Charge		---	17	---	
Q_{gd}	Gate-Drain Charge		---	11	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DD}}=10\text{V}$, $R_G=1\Omega$,	---	22	---	ns
T_r	Rise Time		---	80	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	50	---	
T_f	Fall Time		---	28	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	4960	---	pF
C_{oss}	Output Capacitance		---	328	---	
C_{rss}	Reverse Transfer Capacitance		---	203	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0\text{V}$, Force Current	---	---	120	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=25\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=37\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	35	---	nS
Q_{rr}	Reverse Recovery Charge		---	54	---	nC

Note :

1. The data is tested by a surface mounted diode on a 1 inch² FR-4 board with 2OZ copper.2. The data is tested by pulsed pulse width $\leq 300\text{us}$ duty cycle $\leq 2\%$.

3. The EAS data shows Max. Rating at the test condition is VRMS = 0, VDD = 30V, VG = 10V, Rg = 25Ω,

L = 0.5mH, IAS = 31.5A

4. The power dissipation is limited by junction temperature

The data is theoretically the same as A_{D} and A_{DM} . In real applications, it should be limited by total power.

Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

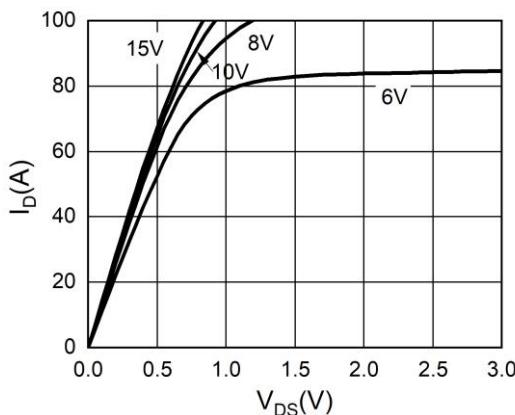


Figure 2. Transfer Characteristics

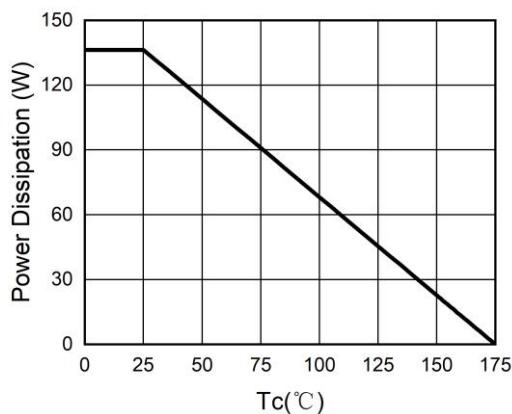
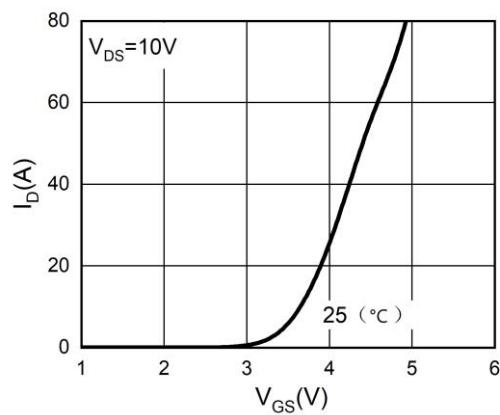


Figure 5. BV_{DSS} vs Junction Temperature

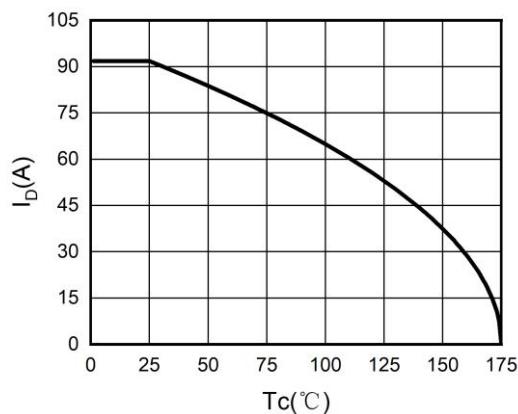


Figure 6. $R_{DS(on)}$ vs Junction Temperature

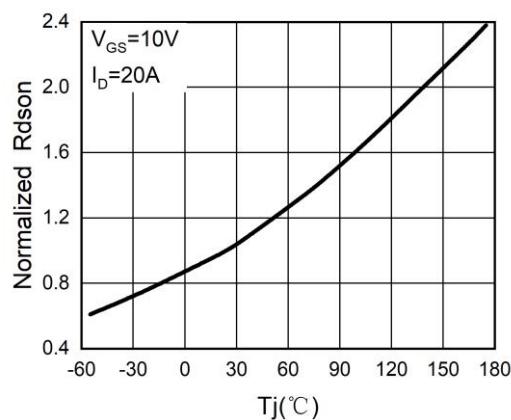
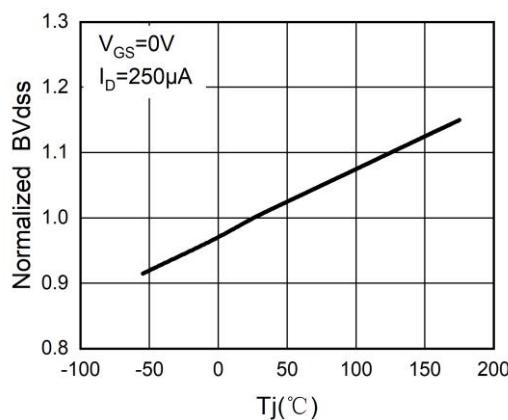
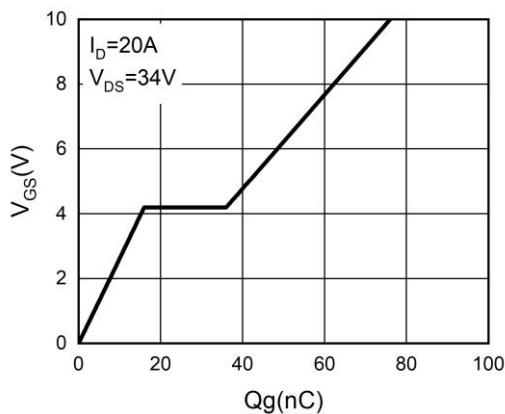
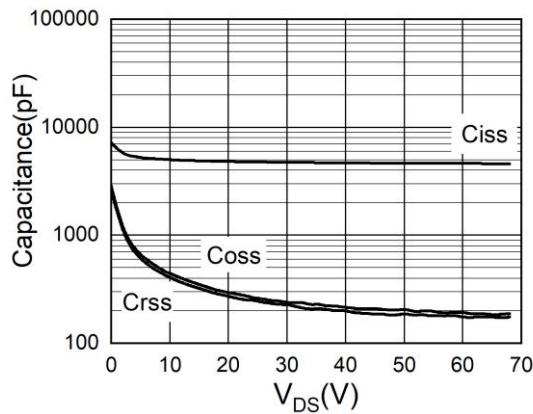
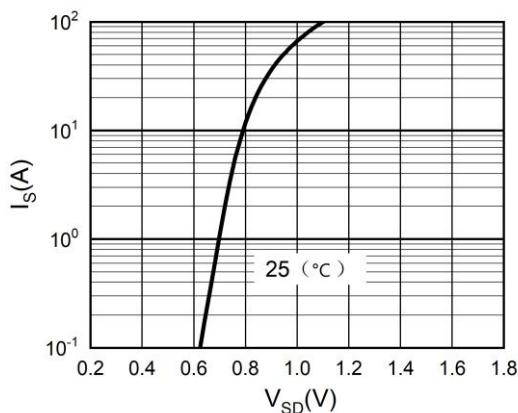
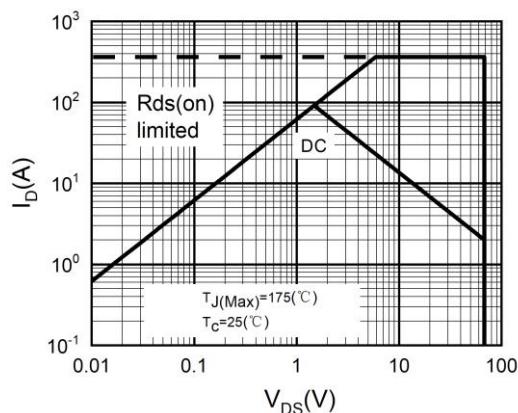
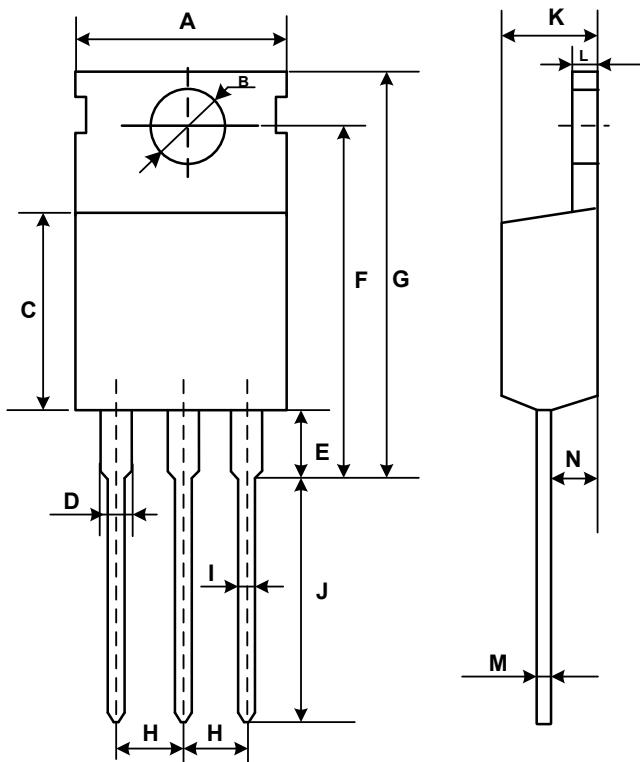


Figure 7. Gate Charge Waveforms**Figure 8. Capacitance****Figure 9. Body-Diode Characteristics****Figure 10. Maximum Safe Operating Area**

Mechanical Dimensions for TO-220**COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.50
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60